TOSHIBA Field Effect Transistor Silicon N Channel MOS Type (p-MOSVI)

2SK3868

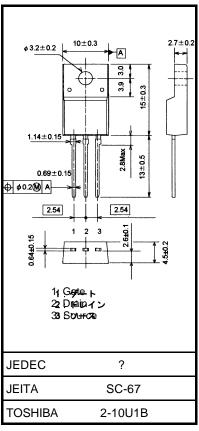
Switching Regulator Applications

Unit: mm

- Low drain-source ON resistance: RDS (ON) = 1.3 (typ.)
- High forward transfer admittance: $|Y_{fs}| = 3S$ (typ.)
- Low leakage current: $IDSS = 100 \mu A (VDS = 500 V)$
- Enhancement-mode: $V_{th} = 2.0 \sim 4.0 \text{ V}$ ($V_{DS} = 10 \text{ V}$, $I_{D} = 1 \text{ mA}$)

Maximum Ratings (Ta = 25°C)

| Characteristics | | Symbol | Rating | Unit | |
|--|------------------------------|------------------|---------|------|--|
| Drain-source voltage | | V_{DSS} | 500 | V | |
| Drain-gate voltage ($R_{GS} = 20 \text{ k}\Omega$) | | V_{DGR} | 500 | V | |
| Gate-source voltage | | V_{GSS} | ±30 | V | |
| Drain current | DC (Note 1) | l _D | 5 | | |
| | Pulse (t = 1 ms) (Note 1) | l _{DP} | 20 | Α | |
| Drain power dissipati | on (Tc = 25°C) | P_{D} | 35 | W | |
| Single pulse avalanche energy (Note 2) | | E _{AS} | 180 | mJ | |
| Avalanche current | | I _{AR} | 5 | Α | |
| Repetitive avalanche energy (Note 3) | | E _{AR} | 3.5 | mJ | |
| Channel temperature | | T _{ch} | 150 | °C | |
| Storage temperature range | | T _{stg} | -55~150 | °C | |



Weight: 1.7 g (typ.)

Thermal Characteristics

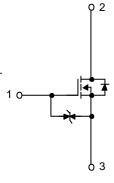
| Characteristics | Symbol | Max | Unit | |
|--|------------------------|------|------|--|
| Thermal resistance, channel to case | R _{th (ch-c)} | 3.57 | °C/W | |
| Thermal resistance, channel to ambient | R _{th (ch-a)} | 62.5 | °C/W | |

Note 1: Please use devices on conditions that the channel temperature is below 150°C.

Note 2: V_{DD} = 90 V, T_{ch} = 25°C(initial), L = 12.2 mH, I_{AR} = 5 A, R_G = 25 Ω

Note 3: Repetitive rating: Pulse width limited by maximum channel temperature

This transistor is an electrostatic sensitive device. Please handle with caution.





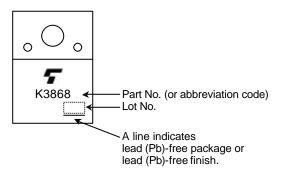
Electrical Characteristics (Ta = 25°C)

| Char | acteristics | Symbol | Test Condition | Min | Тур. | Max | Unit |
|-------------------------------|----------------|----------------------|--|-----|------|-----|------|
| Gate leakage current | | lgss | $V_{GS} = \pm 25 V, V_{DS} = 0 V$ | _ | _ | ±10 | μΑ |
| Gate-source breakdown voltage | | V (BR) GSS | $I_{G} = \pm 10 \mu A, V_{DS} = 0 V$ | ±30 | _ | _ | V |
| Drain cut-off curi | rent | l _{DSS} | $V_{DS} = 500 \text{ V}, V_{GS} = 0 \text{ V}$ | _ | _ | 100 | μΑ |
| Drain-source bre | akdown voltage | V (BR) DSS | $I_D = 10 \text{ mA}, V_{GS} = 0 \text{ V}$ | 500 | _ | _ | V |
| Gate threshold v | oltage | V_{th} | $V_{DS} = 10 \text{ V}, I_D = 1 \text{ mA}$ | 2.0 | _ | 4.0 | V |
| Drain-source ON | l resistance | R _{DS (ON)} | $V_{GS} = 10 \text{ V}, I_D = 2.5 \text{ A}$ | _ | 1.3 | 1.7 | Ω |
| Forward transfer | admittance | Y _{fs} | $V_{DS} = 10 \text{ V}, I_D = 2.5 \text{ A}$ | 1.5 | 3.0 | _ | S |
| Input capacitance | | C _{iss} | V _{DS} = 25 V, V _{GS} = 0 V, f = 1 MHz | _ | 550 | _ | pF |
| Reverse transfer capacitance | | C _{rss} | | _ | 7 | _ | |
| Output capacitance | | C _{oss} | | _ | 70 | _ | |
| Switching time | Rise time | t _r | $\begin{array}{c} 10 \text{ V} \\ \text{VGS} \\ 0 \text{ V} \\ \end{array} \begin{array}{c} \text{ID} = 2.5 \text{ A} \\ \text{VOUT} \\ \end{array} \begin{array}{c} \text{RL} = \\ 90 \Omega \\ \end{array}$ $\text{VDD} \approx 225 \text{ V}$ Duty $\leq 1\%$, $t_{\text{W}} = 10 \mu\text{s}$ | _ | 10 | | |
| | Turn-on time | t _{on} | | _ | 20 | | |
| | Fall time | t _f | | _ | 10 | _ | ns |
| | Turn-off time | t _{off} | | _ | 50 | _ | |
| Total gate charge | | Qg | | _ | 16 | _ | |
| Gate-source charge | | Q _{gs} | $V_{DD} \approx 400 \text{ V}, V_{GS} = 10 \text{ V}, I_D = 5 \text{ A}$ | | 10 | | nC |
| Gate-drain charge | | Q _{gd} | | | 6 | | |

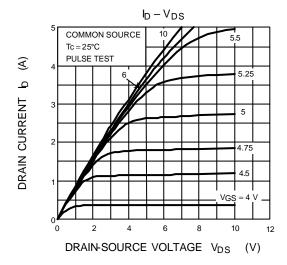
Source-Drain Ratings and Characteristics (Ta = 25°C)

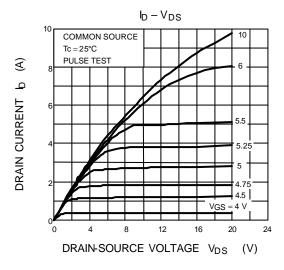
| Characteristics | Symbol | Test Condition | Min | Тур. | Max | Unit |
|---|------------------|--|-----|------|------|------|
| Continuous drain reverse current (Note 1) | I _{DR} | _ | _ | _ | 5 | А |
| Pulse drain reverse current (Note 1) | I _{DRP} | _ | _ | _ | 20 | Α |
| Forward voltage (diode) | V_{DSF} | $I_{DR} = 5 \text{ A}, V_{GS} = 0 \text{ V}$ | _ | _ | -1.7 | V |
| Reverse recovery time | t _{rr} | $I_{DR} = 5 A, V_{GS} = 0 V,$ | _ | 150 | _ | ns |
| Reverse recovery charge | Q_{rr} | dl _{DR} /dt = 100 A/μs | _ | 0.3 | _ | μС |

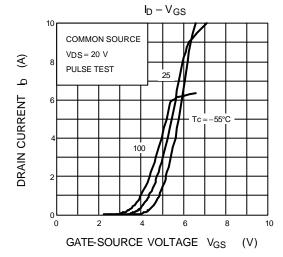
Marking

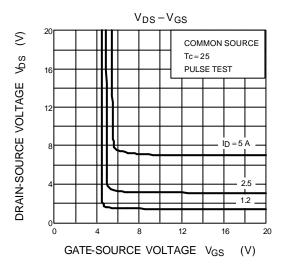


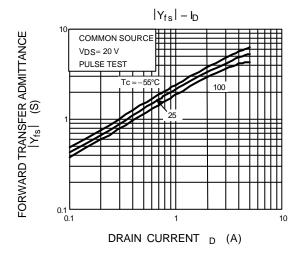
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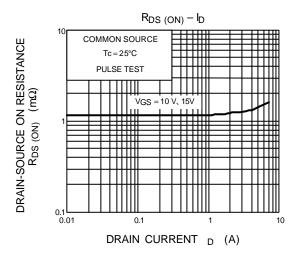


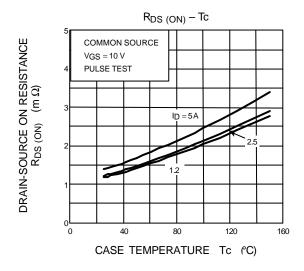


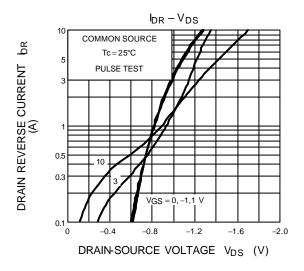


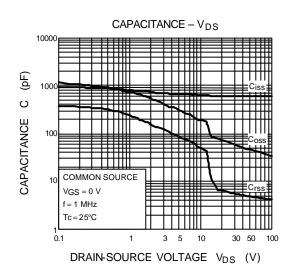


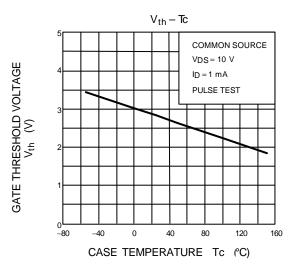


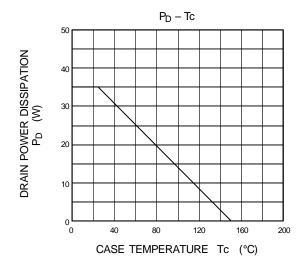


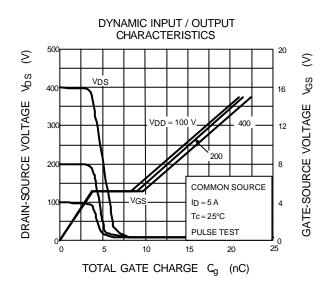




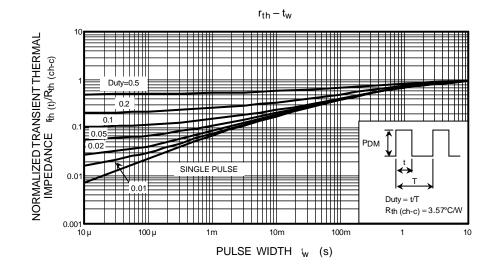


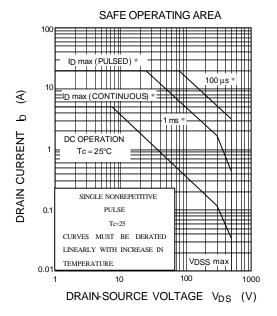


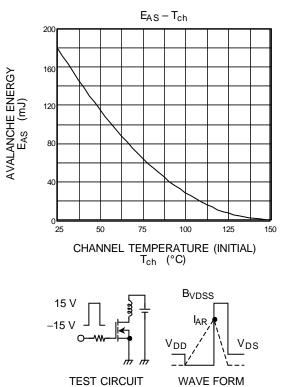




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$$R_G = 25 \Omega$$

 $V_{DD} = 90 \text{ V, L} = 12.2 \text{mH}$ $? AS = \frac{1}{2} \cdot L \cdot I^2 \cdot \left(\frac{B_{VDSS}}{B_{VDSS} - V_{DD}} \right)$

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